

### **Abstract of the Disclosure**

Methods for producing a flip chip package by prepackaging one or more dice on a semiconductor wafer are provided. An embodiment of the method includes applying an adhesive to a first side of a finished wafer, where a number of dice are located. The active layer of the dice is on the first side of the finished wafer. The method further includes forming an array of conductive elements within the adhesive, where the array of conductive elements is electrically coupled to an array of connection pads on a die. The wafer can be diced to provide pre-packaged chips. To provide greater mounting densities, two or more dice may be coupled before application of the adhesive layer.

5

"Express Mail" mailing label number: EV298565265US

Date of Deposit: November 26, 2003

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the Commissioner for Patents, Mail Stop Patent Application, P.O. Box 1450, Alexandria, VA 22313-1450.